High Performance ASIC Cooling Solutions w/Thermal Tape Attachment*

DIGI-KEY PART # ATS1338-ND

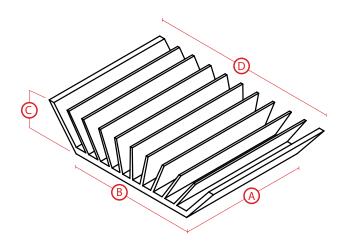
ATS PART # ATS-56007-C3-R0

Features & Benefits

maxiFLOW[™] design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling

Designed specifically for ASIC package and their unique cooling requirements

Comes preassembled with high performance thermal interface material





Thermal Performance Table

AIR VELOCITY		THERMAL RESISTANCE		
FT/MIN	M/S	°C/W (UNDUCTED)	°C/W (DUCTED)	
200	1.0	2.4	1.7	
300	1.5	2		
400	2.0	1.7		
500	2.5	1.5		
600	3.0	1.3		
700	3.5	1.2		
800	4.0	1.1		

Product Details[†]

DIMENSION A	DIMENSION B	DIMENSION C [§]	DIMENSION D	TIM [‡]	FINISH
45	45	15	64	C675	BLACK-ANODIZED

For further technical information, please contact Advanced Thermal Solutions, Inc. at **1-781-769-2800** or **www.qats.com**

* RoHS Compliant

‡ TIM = Thermal Interface Material

† Dimensions are measured in millimeters

Dimension C = the height of the heat sink shown above

and does not include the height of the attachment method





To place an order, please visit www.digikey.com